

SEMI E142 Substrate Mapping Standard and ALPS 3

SEMI approved the new [SEMI E142 Substrate Mapping standard](#) in October 2004.

[ALPS 3](#) is based on SEMI E142 and supports all the features described there. ALPS 3 is applicable to all final manufacturing equipment, including but not limited to: bump inspection equipment, wafer probers, die bonders, wire bonders, strip testers, laser markers, and singulation equipment. Additionally, the mapping structure can handle multi-project wafers, stacked die, and multi-die strips/substrates. ALPS 3 will be used to integrate wafer sort facility and the assembly and test facility. ALPS 3 will also provide a means for reliable, encrypted transfer of data between plants.

We co-authored [an article in Chip Scale Review July 2005 called New Standards Further Supply Chain Integration](#), which contains some useful information.

You can download the SEMI E142-0706 standard from the [SEMI web site](#). Go to

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SEMI E142-0706

Press [Next Page](#) if necessary to locate SEMI E142. Follow the instructions for download. You will need an account if someone at your organization has one, or if not, you can just pay \$50 by credit card.

Once you have downloaded the PDF version of the standard, you will also need the schema which is listed in the [supplemental materials section](#) under XML Schema for SEMI E142.1-**0706**.

To learn more about the development of SEMI E142 and ongoing activities please visit the [Sort Map TF meeting room](#) on the SEMI website. Click on [Library](#) on the left and browse the latest entries to learn what is going on in the Sort Map TF and to download documents.